

in Silicone resin

Solvent based coatings

Evonik Tego formulation No. 3002

Rev. Number: 01.01

08/07

Function	Product	Producer	PBW
Silicone epoxy hybrid resin	SILIKOPON® EW	Evonik	26.30
Copper chromite black spinel	HEUCODUR® Black 9-100	Heubach	10.40
Mica/quartz/chlorite filler	Plastorit® 0000	Imerys	10.20
Magnesium silicate	Microtalc™ IT Extra	Elementis	4.00
Anticorrosive pigment	HEUCOPHOS® ZPO	Heubach	5.00
Solvent	Solvesso™ 100	ExxonMobil	13.00
Rheology modifier	AEROSIL® R 972	Evonik	0.90
Solvent	Methoxypropyl acetate		3.80
Grind.			
Silicone epoxy hybrid resin	SILIKOPON® EW	Evonik	15.80
Solvent	Butyl acetate		4.60
Solvent	Xylene		6.00
Add while stirring.			

100.00

Gf-SB10_007-01_01A

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